

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	SECURITY AGREEMENT
CONVEYING PARTY DATA	
Name	Execution Date
ATEK Plastics, Inc.	11/10/2011
RECEIVING PARTY DATA	
Name:	Madison Capital Funding LLC, as Agent
Street Address:	30 South Wacker Drive, Suite 3700
City:	Chicago
State/Country:	ILLINOIS
Postal Code:	60606
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12757691
CORRESPONDENCE DATA	
Fax Number:	(312)902-1061
Phone:	312.577.8034
Email:	oscar.ruiz@kattenlaw.com
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>	
Correspondent Name:	Oscar Ruiz c/o Katten Muchin Rosenman
Address Line 1:	525 West Monroe Street
Address Line 4:	Chicago, ILLINOIS 60661
ATTORNEY DOCKET NUMBER:	214338-21
NAME OF SUBMITTER:	Oscar Ruiz
Total Attachments: 5 source=Patent Security Agreement#page1.tif source=Patent Security Agreement#page2.tif source=Patent Security Agreement#page3.tif source=Patent Security Agreement#page4.tif source=Patent Security Agreement#page5.tif	

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PATENT SECURITY AGREEMENT

THIS PATENT SECURITY AGREEMENT (this "**Agreement**") made as of this 10th day of November, 2011, by ATEK PLASTICS, INC., a Minnesota corporation ("**Grantor**"), in favor of MADISON CAPITAL FUNDING LLC, in its capacity as Agent for the Lenders party to the Credit Agreement (defined below) (in such capacity, "**Grantee**"):

W I T N E S S E T H

WHEREAS, The MedTech Group, Inc., a New Jersey corporation ("**MedTech**"), and Advanced Polymers, Inc., a New Hampshire corporation ("**Advanced Polymers**"; Advanced Polymers and MedTech are sometimes hereinafter referred to individually as a "**Borrower**" and collectively as the "**Borrowers**"), the financial institutions party thereto from time to time (together with their respective successors and assigns, "**Lenders**") and Grantee have entered into that certain Amended and Restated Credit Agreement dated as of September 8, 2010 (as amended, restated, supplemented or otherwise modified from time to time, the "**Credit Agreement**"), pursuant to which Grantee and Lenders have agreed, subject to the terms and conditions thereof, to make certain loans to, and other credit accommodations in favor of, Borrowers (collectively, the "**Loans**").

WHEREAS, pursuant to the terms of that certain Amended and Restated Guarantee and Collateral Agreement dated as of September 8, 2010 between Grantor (as a party by joinder thereto), certain Affiliates of Grantor and Grantee (as the same may be amended, restated, supplemented or otherwise modified and in effect from time to time, the "**Guarantee and Collateral Agreement**"), Grantor has granted to Grantee, for its benefit and the benefit of Lenders, a security interest and lien upon all or substantially all assets of Grantor, including all right, title and interest of Grantor in, to and under all now owned and hereafter acquired Patents (as defined in the Guarantee and Collateral Agreement), and all products and proceeds thereof, to secure the payment of all amounts owing by Grantor under the Credit Agreement.

NOW, THEREFORE, in consideration of the premises set forth herein and for other good and valuable consideration, receipt and sufficiency of which are hereby acknowledged, Grantor agrees as follows:

1. Incorporation of Credit Agreement and Guarantee and Collateral Agreement. The Credit Agreement and Guarantee and Collateral Agreement and the terms and provisions thereof are hereby incorporated herein in their entirety by this reference thereto. All capitalized terms used herein but not otherwise defined herein shall have the respective meanings ascribed to such terms in the Guarantee and Collateral Agreement.

2. Grant and Reaffirmation of Grant of Security Interests. To secure the payment and performance of the Obligations (as defined in the Credit Agreement), Grantor hereby grants to Grantee, for its benefit and the benefit of Lenders, and hereby reaffirms its prior grant pursuant to the Guarantee and Collateral Agreement of, a continuing security interest in Grantor's entire right, title and interest in and to the following (all of the following items or types

of property being herein collectively referred to as the “**Patent Collateral**”), whether now owned or existing or hereafter created, acquired or arising:

(i) each Patent listed on Schedule A annexed hereto, together with any reissues, continuations or extensions thereof; and

(ii) all products and proceeds of the foregoing, including without limitation, any claim by Grantor against third parties for past, present or future infringement or dilution of any Patent.

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IN WITNESS WHEREOF, Grantor has duly executed this Agreement as of the date first written above.

ATEK PLASTICS, INC., a Minnesota
corporation

By: 

Name: Michael Z. Barkin

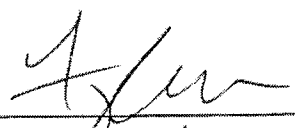
Title: Vice President and Secretary

Patent Security Agreement

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Agreed and Accepted
As of the Date First Written Above:

**MADISON CAPITAL FUNDING LLC, as
Agent**

By: 
Name: FARAZ KAMRAN
Title: DIRECTOR

Patent Security Agreement

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SCHEDULE A

Patent Registrations

None.

Patent Applications

Patent Application Description	Application Number	Application Date	Jurisdiction
IN-MOLD LABELING APPARATUS AND METHOD	12/757,691 20110169192	April 9, 2010	United States